

BOM CHANGE SUMMARY

- ▶ From 4 BOM at UG1 to 1 BOM at AEK.
 - 4 different Adhesive material at UG1 will become 1 Adhesive material at AEK

Assembly Site	From - UNISEM Malaysia (UG1)	To - ASE Korea (AEK)
Wire	Au/1.0	Au/1.0
Die Attach	Ablestik 2815A conductive Hysol QMI 519 conductive Sumitomo CRM 1076NS conductive Sumitomo CRM 1076DJ conductive	Hitachi EN 4900GC conductive
Mold Compound	Sumitomo G770HCD	Sumitomo G700LYT
Plating	100Sn	100Sn

BOM CHANGE SUMMARY

► BOM for 0.8 mil wire

Assembly Site	From - UNISEM Malaysia (UG1)	To - ASE Korea (AEK)
Wire	Au/0.8	Au/0.8
Die Attach	Hysol QMI 519 conductive	Hitachi EN 4900GC conductive
Mold Compound	Sumitomo G770HCD	Sumitomo G700LYT
Plating	100Sn	100Sn

BOM CHANGE SUMMARY

► BOM for NiPdAu Terminal Finish Composition

Assembly Site	From - UNISEM Malaysia (UG1)	To - ASE Korea (AEK)
Wire	Au/1.0	Au/1.0
Die Attach	Hysol QMI 519 conductive	Hitachi EN 4900GC conductive
Mold Compound	Sumitomo G770HCD	Sumitomo G700LYT
Plating	Ni_Pd_Au	Ni_Pd_Au